Switching Diode

BAS16P2T5G

The BAS16P2T5G Switching Diode is a spin-off of our popular SOT-23 three-leaded device. It is designed for switching applications and is housed in the SOD-923 surface mount package. This device is ideal for low-power surface mount applications, where board space is at a premium.

Features

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V_{R}	100	Vdc
Peak Forward Current	ΙF	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

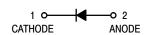
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA}	520	°C/W
	P _D	240	mW
Thermal Resistance, Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA}	175	°C/W
	P _D	710	mW
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

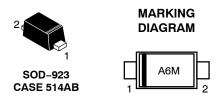
- Mounted onto a 4 in square FR-4 board 10 mm sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.
- Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.



ON Semiconductor®

www.onsemi.com





A6 = Specific Device Code M = Month Code

ORDERING INFORMATION

Device	Package	Shipping [†]
BAS16P2T5G	SOD-923 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

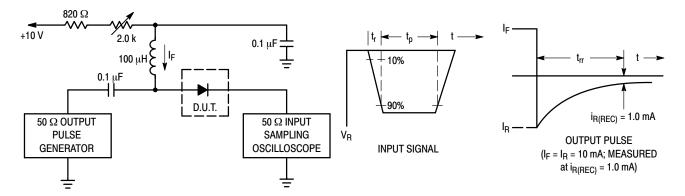
BAS16P2T5G

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Reverse Voltage Leakage Current ($V_R = 75 \text{ Vdc}$) ($V_R = 100 \text{ Vdc}$) ($V_R = 75 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$) ($V_R = 25 \text{ Vdc}$, $T_J = 150^{\circ}\text{C}$)	I _R	- - - -	1.0 100 50 30	μAdc
Reverse Breakdown Voltage (I _{BR} = 100 μAdc)	V _(BR)	100	-	Vdc
Forward Voltage ($I_F = 1.0 \text{ mAdc}$) ($I_F = 10 \text{ mAdc}$) ($I_F = 50 \text{ mAdc}$) ($I_F = 150 \text{ mAdc}$)	V _F	- - -	715 855 1000 1250	mV
Diode Capacitance (V _R = 0, f = 1.0 MHz)	C _D	_	2.0	pF
Forward Recovery Voltage (I _F = 10 mAdc, t _r = 20 ns)	V _{FR}	=	1.75	Vdc
Reverse Recovery Time $(I_F = I_R = 10 \text{ mAdc}, R_L = 50 \Omega)$	t _{rr}	=	6.0	ns
Stored Charge (I _F = 10 mAdc to V _R = 5.0 Vdc, R_L = 500 Ω)	Q _S	I	45	pC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

BAS16P2T5G



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so $I_{R(peak)}$ is equal to 10 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

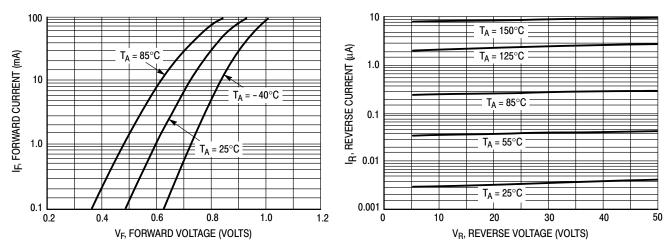


Figure 2. Forward Voltage

Figure 3. Leakage Current

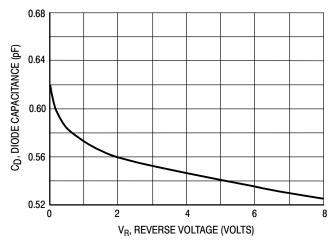


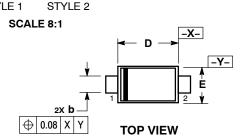
Figure 4. Capacitance

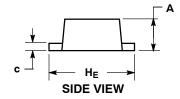


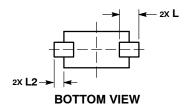


SOD-923 CASE 514AB ISSUE D

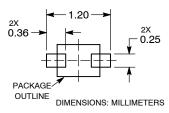
DATE 03 SEP 2020







SOLDERING FOOTPRINT*



See Application Note AND8455/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

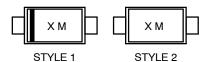
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD MAXIMUM LEAD I HICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

 DIMENSION L WILL NOT EXCEED 0.30mm.

	MILLIMETERS				INCHES		
DIM	MIN	NOM	MAX	MIN	MOM	MAX	
Α	0.34	0.37	0.40	0.013	0.015	0.016	
b	0.15	0.20	0.25	0.006	800.0	0.010	
С	0.07	0.12	0.17	0.003	0.005	0.007	
D	0.75	0.80	0.85	0.030	0.031	0.033	
Е	0.55	0.60	0.65	0.022	0.024	0.026	
HE	0.95	1.00	1.05	0.037	0.039	0.041	
L	0.19 REF		0	.007 RE	F		
L2	0.05	0.10	0.15	0.002	0.004	0.006	

GENERIC MARKING DIAGRAM*



Χ = Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 2: NO POLARITY STYLE 1: PIN 1. CATHODE (POLARITY BAND) 2. ANODE

DOCUMENT NUMBER:	98AON23284D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.	
DESCRIPTION:	SOD-923, 1.0X0.6X0.37, MAX HEIGHT 0.40		PAGE 1 OF 1

ON Semiconductor and (III) are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. Onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer pu

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT: Email Requests to: orderlit@onsemi.com

onsemi Website: www.onsemi.com

TECHNICAL SUPPORT North American Technical Support: Voice Mail: 1 800-282-9855 Toll Free USA/Canada Phone: 011 421 33 790 2910

Europe, Middle East and Africa Technical Support:

Phone: 00421 33 790 2910

For additional information, please contact your local Sales Representative